

Gap Filler

Product Name	Description	Key Attributes	Thermal Conductivity (W/m•K)	Viscosity at 25°C (cP)	Dielectric Strength (V/25 µm)	Flammability Rating	Recommended Cure
BERGQUIST GAP FILLER 1100SF	Silicone-free, thermally conductive liquid gap filling material	<ul style="list-style-type: none"> No silicone outgassing or extraction Ultra-conforming material designed for fragile and low-stress applications Ambient and accelerated cure schedules 100% solids – no cure by-products 	1.1	450,000	400	UL 94 V-0	24 hr. at 25°C
BERGQUIST GAP FILLER 1500	Thermally conductive liquid gap filling material	<ul style="list-style-type: none"> Optimized shear thinning characteristics for ease of dispensing Excellent slump resistance Ultra-conforming with excellent wet-out for low-stress interface applications 100% solids – no cure by-products Excellent low- and high-temperature mechanical and chemical stability Ambient and accelerated cure schedules 	1.8	25,000	400	UL 94 V-0	3 days at 25°C
BERGQUIST GAP FILLER 1500 LV	Thermally conductive liquid gap filling material	<ul style="list-style-type: none"> Low volatility for silicone sensitive applications Ultra-conforming with excellent wet-out 100% solids – no cure by-products Excellent low- and high-temperature, chemical and mechanical stability Ambient or accelerated cure schedules 	1.8	20,000	400	UL 94 V-0	8 hr. at 25°C
BERGQUIST GAP FILLER 3500LV	Thermally conductive liquid gap filling material	<ul style="list-style-type: none"> Low volatility for outgassing sensitive applications Ultra-conforming with excellent wet-out for low-stress interfaces on applications 100% solids – no cure by-products Ambient or accelerated cure schedules 	3.5	45,000	275	UL 94 V-0	24 hr. at 25°C
BERGQUIST GAP FILLER 3500S35	Thermally conductive liquid gap filling material	<ul style="list-style-type: none"> High thermal performance Thixotropic nature makes it easy to dispense Ultra-conforming material designed for fragile and low-stress applications Ambient or accelerated cure schedules 	3.6	150,000	275	UL 94 V-0	15 hr. at 25°C
BERGQUIST GAP FILLER 4000	Thermally conductive liquid gap filling material	<ul style="list-style-type: none"> High thermal performance Extended working time for manufacturing flexibility Ultra-conforming with excellent wet-out 100% solids – no cure by-products Excellent low- and high-temperature, chemical and mechanical stability Ambient or accelerated cure schedules 	4.0	50,000	450	UL 94 V-0	24 hr. at 25°C

Henkel AG & Co. KGaA
 Henkelstraße 67
 40589 Düsseldorf | Germany

Phone: +1 952 486 6313
 E-mail: electronics@henkel.com
www.henkel-adhesives.com/electronics

